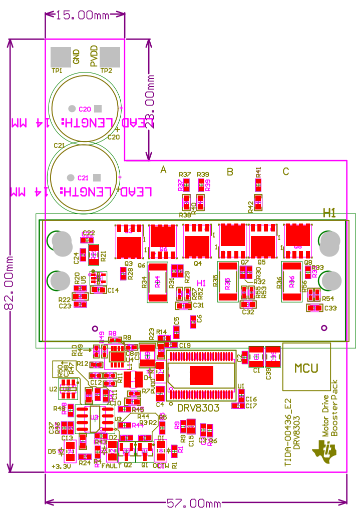
ZZ4 ■ These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.
ZZ3 ■ These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.
ZZ2 ■ These assemblies are ESD sensitive, ESD precautions shall be observed.



Layer Stack Up Detail for: TIDA-00436.PcbDoc

Layer Name	Gerber Document	Copper Thickness	Dielectric Material
Top Solder Mask	(.GTS)		Solder Resist
Top Layer	(.GTL)	2.8mil	
			FR-4
POWER	(.G1)	2.8mil	
			FR-4
GND	(.G2)	2.8mil	
			FR-4
Bottom Layer	(.GBL)	2.8mil	
Bottom Solder Mask	(.GBS)		Solder Resist

DESIGN INFORMATION

BOARD SIZE (REFER ALSO ARRAY/PANEL PROFILING INFORMATION)
2244.09MIL X 3228.34MIL
Number of Layers : 4
MIN. TRACK WIDTH: 8 MIL
MIN. CLEARANCE: 6 MIL
MIN. VIA PAD SIZE: 19.685 MIL
It is not an impedance controlled board.
MINIMUM ANNULAR RING 0.127mm (5MIL) EXTERNAL
PER IPC-D-275 CLASS 2 LEVEL C
REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL

MATERIAL:
[X] FR-408 [ ] FR-4 High Tg [ ] OTHER ______
THICKNESS: [X] 63 MIL (1.6mm) +/-10% [ ] OTHER ______
TOLERANCE: [X] ANSI IPC-6012 TYPE 3 CLASS 2
[ ] OTHER +/- ______
BOW & TWIST: [X] ANSI IPC-6012 TYPE 3 CLASS 2
[ ] OTHER +/- ______
COPPER THICKNESS (FINISHED):
OUTER: [ ] 1.4MIL (1oz) [ ] 2MIL (1.4oz) [X] 2.8MIL (2oz)
INNER SIGNAL: [ ] 1.4MIL (1oz) [X] 2.8MIL (2oz) [ ] N/A
DRILLING:
REFERENCE: [X] AS SHOWN [X] NC_DRILL FILES
PTH MIN COPPER THICKNESS: [X] 1MIL [ ] OTHER ______
BOARD FINISH:
SILKSCREEN: [X] TOP [X] BOTTOM
SILKSCREEN COLOR: [X] WHITE [ ] OTHER ______
SOLDER RESIST COLOR:
[X] GREEN [ ] BLUE [ ] OTHER ______
SURFACE FINISH: [X] IMMERSION GOLD (ENIG) [ ] ENEPIG
[ ] IMM. TIN/SILVER OR EQUIV [ ] OTHER ______
ARRAY/PANEL: [ ] CUT AND TRIM PER MECH LAYER 1
[ ] N.C. ROUTE [X] V. SCORE
CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBS TO MEET OR EXCEED THE REQUIREMENTS OF:
[X] ANSI IPC-A-600F CLASS -> [ ] 1 [X] 2 [ ] 3
[X] UL 94V-0 [X] RoHS [ ] OTHER PER ORDER
ADDITIONAL REQUIREMENTS:
MICROSECTION: [ ] YES VIA TENTING: YES [X] NO [ ]
BARE BOARD ELEC. TEST: [ ] NONE [X] REQUIRED [ ] PER ORDER
MANUFACTURER'S UL: [ ] RAIL [ ] METAL [X] SILK

TEXAS INSTRUMENTS

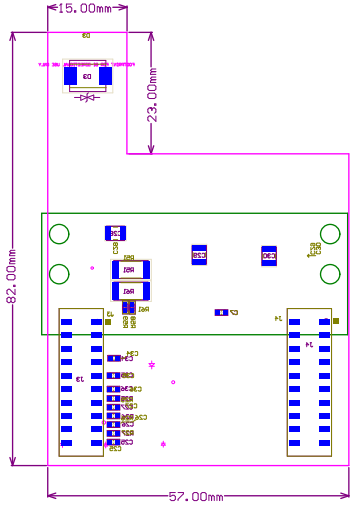
PROJECT TITLE: TIDA-00436_E2
DESIGNED FOR:
FILE NAME: TIDA-00436.PcbDoc
ENGINEER: Nelson
LAYOUT BY:
SCALE: 1.00
ALTIUM DESIGNER VERSION: 10.0.0.27009

COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
ASSEMBLY VARIANT: [No Variations]

PCB ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00436	REV: E2	SVN REV: Not in Version Control	
LAYER NAME = ASSEMBLY TOP / TOP OVERLAY				
PLOT NAME = Top Assembly Drawing	GENERATED : 3/13/2015 5:30:31 PM		TEXAS INSTRUMENTS	

Layer Stack Up Detail for: TIDA-00436.PcbDoc

Layer Name	Gerber Document	Copper Thickness	Dielectric Material
Top Solder Mask	(.GTS)		Solder Resist
Top Layer	(.GTL)	2.8mil	
			FR-4
POWER	(.G1)	2.8mil	
			FR-4
GND	(.G2)	2.8mil	
			FR-4
Bottom Layer	(.GBL)	2.8mil	
Bottom Solder Mask	(.GBS)		Solder Resist



DESIGN INFORMATION

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2244.09MIL X 3228.34MIL
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PER IPC-D-275 CLASS 2 LEVEL C
REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL

MATERIAL:
[X] FR-408 [ ] FR-4 High Tg [ ] OTHER _____
THICKNESS: [X] 63 MIL (1.6mm) +/-10% [ ] OTHER _____
TOLERANCE: [X] ANSI IPC-6012 TYPE 3 CLASS 2
[ ] OTHER +/- _____
BOW & TWIST: [X] ANSI IPC-6012 TYPE 3 CLASS 2
[ ] OTHER +/- _____
COPPER THICKNESS (FINISHED):
OUTER: [ ] 1.4MIL (1oz) [ ] 2MIL (1.4oz) [X] 2.8MIL (2oz)
INNER SIGNAL: [ ] 1.4MIL (1oz) [X] 2.8MIL (2oz) [ ] N/A
DRILLING:
REFERENCE: [X] AS SHOWN [X] NC_DRILL FILES
PTH MIN COPPER THICKNESS: [X] 1MIL [ ] OTHER _____
BOARD FINISH:
SILKSCREEN: [X] TOP [X] BOTTOM
SILKSCREEN COLOR: [X] WHITE [ ] OTHER _____
SOLDER RESIST COLOR:
[X] GREEN [ ] BLUE [ ] OTHER _____
SURFACE FINISH: [X] IMMERSION GOLD (ENIG) [ ] ENEPIG
[ ] IMM. TIN/SILVER OR EQUIV [ ] OTHER _____
ARRAY/PANEL: [ ] CUT AND TRIM PER MECH LAYER 1
[ ] N.C. ROUTE [X] V. SCORE
CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBS TO MEET OR EXCEED THE REQUIREMENTS OF:
[X] ANSI IPC-A-600F CLASS -> [ ] 1 [X] 2 [ ] 3
[X] UL 94V-0 [X] RoHS [ ] OTHER PER ORDER
ADDITIONAL REQUIREMENTS:
MICROSECTION: [ ] YES VIA TENTING: YES [X] NO [ ]
BARE BOARD ELEC. TEST: [ ] NONE [X] REQUIRED [ ] PER ORDER
MANUFACTURER'S UL: [ ] RAIL [ ] METAL [X] SILK

COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED
ASSEMBLY VARIANT: [No Variations]

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TEXAS INSTRUMENTS

PROJECT TITLE: TIDA-00436_E2

DESIGNED FOR:

FILE NAME: TIDA-00436.PcbDoc

ENGINEER: Nelson

LAYOUT BY:

SCALE: 1.00

ALTIUM DESIGNER VERSION: 10.0.0.27009